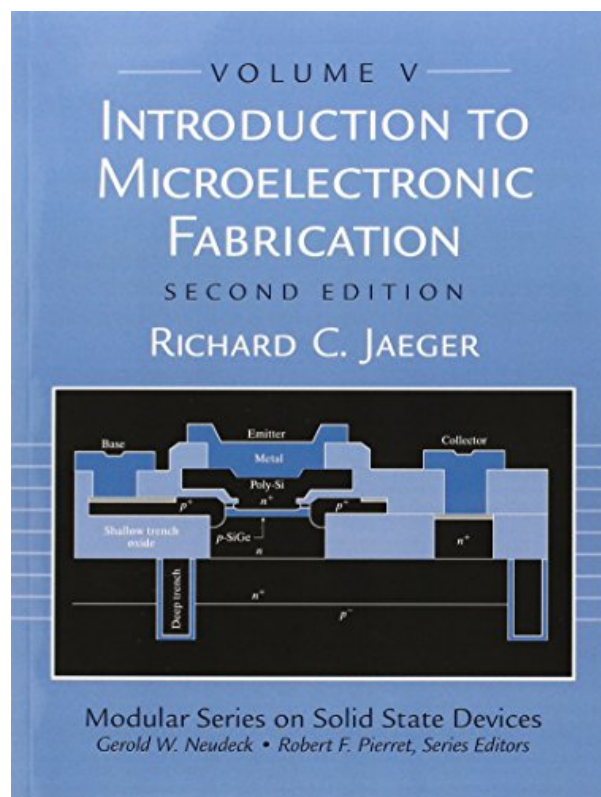


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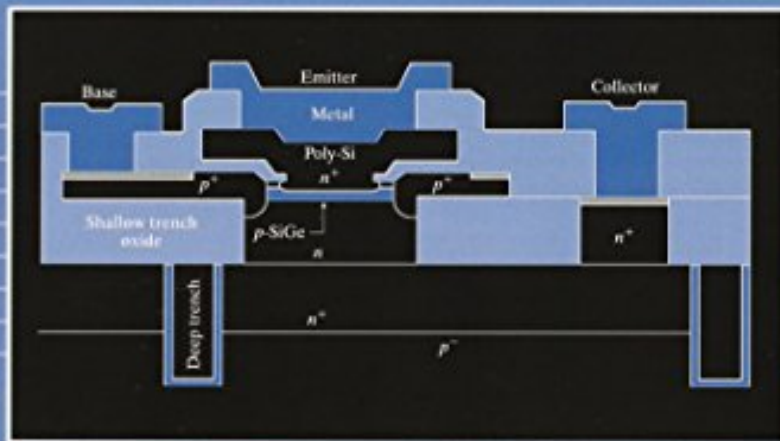


VOLUME V

# INTRODUCTION TO MICROELECTRONIC FABRICATION

SECOND EDITION

RICHARD C. JAEGER



Modular Series on Solid State Devices  
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